

**Polymer
PTC Devices**

Surface mount fuses

Shanghai Wayon Thermo/Electro Materials Co.,Ltd.
10th Floor, No.201, New Jinqiao Road, Shanghai 201206,China
Tel: 86-21- 50320161 58995165 Fax: 86-21-50320266
E-mail: market@way-on.com [Http://www.way-on.com](http://www.way-on.com)



LP-ISM050

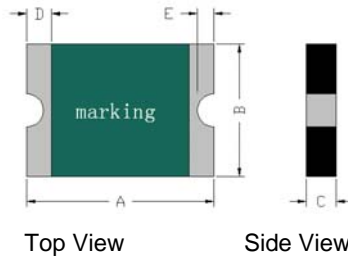
Features

- Small size of 0805
- Lead-free and compliant with the European Union RoHS Directive 2002/95/EC
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL pending



Product Dimensions (mm)

| Part number | A Max. | B Max. | C Max. | D Min. | E Min. | Part marking |
|-------------|-----------|-----------|-----------|-----------|-----------|--------------|
| LP-ISM050 | 2.20 | 1.50 | 1.25 | 0.10 | 0.20 | 4 |

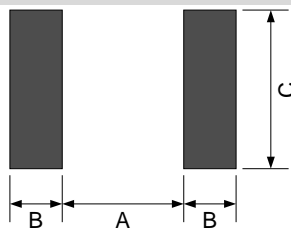


Electrical Characteristics

| Part number | I _H (A) | I _T (A) | V _{max} (V) | I _{max} (A) | T _{trip} Current(A) Time(S) | Pd _{typ} (W) | R _{min} (Ω) | R _{1max} (Ω) |
|-------------|-----------------------|-----------------------|-------------------------|-------------------------|--|--------------------------|-------------------------|--------------------------|
| LP-ISM050 | 0.50 | 1.00 | 6.00 | 40.0 | 8.00 0.10 | 0.5 | 0.15 | 0.85 |

I_H=Hold current: maximum current at which the device will not trip at 25°C still air.
I_T=Trip current: minimum current at which the device will always trip at 25°C still air.
V_{max}=Maximum voltage device can withstand without damage at rated current.
I_{max}=Maximum fault current device can withstand without damage at rated voltage.
T_{trip}=Maximum time to trip(s) at assigned current.
Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
R_{min}=Minimum device resistance at 25°C prior to tripping.
R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

| Part number | A (mm) | B (mm) | C (mm) |
|-------------|-----------|-----------|-----------|
| LP-ISM050 | 1.20 | 1.00 | 1.50 |

* Recommended reflow methods: IR, Vapor phase, hot air oven.
* Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

Package Information

Tape & Reel: 4000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

